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With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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N-Channel Power MOSFET

700V, 4.5A, 0.9Ω

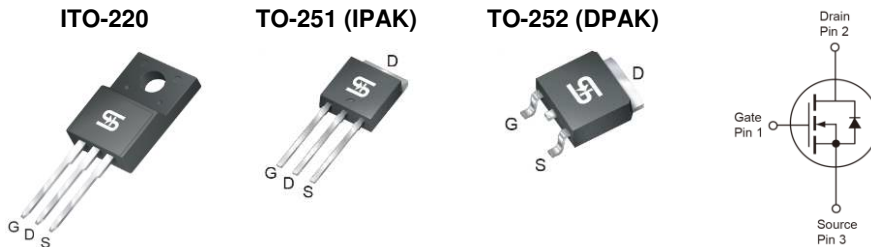
FEATURES

- Super-Junction technology
- High performance due to small figure-of-merit
- High ruggedness performance
- High commutation performance

APPLICATION

- Power Supply
- Lighting

KEY PERFORMANCE PARAMETERS		
PARAMETER	VALUE	UNIT
V_{DS}	700	V
$R_{DS(on)}$ (max)	0.9	Ω
Q_g	9.7	nC



Notes: MSL 3 (Moisture Sensitivity Level) for TO-252 (DPAK) per J-STD-020.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$ unless otherwise noted)				
PARAMETER	SYMBOL	IPAK/DPAK	ITO-220	UNIT
Drain-Source Voltage	V_{DS}	700		V
Gate-Source Voltage	V_{GS}	±30		V
Continuous Drain Current ^(Note 1)	I_D	$T_C = 25^\circ\text{C}$	4.5	A
		$T_C = 100^\circ\text{C}$	2.7	
Pulsed Drain Current ^(Note 2)	I_{DM}	13.5		A
Total Power Dissipation @ $T_C = 25^\circ\text{C}$	P_{DTOT}	50	20	W
Single Pulsed Avalanche Energy ^(Note 3)	E_{AS}	64		mJ
Single Pulsed Avalanche Current ^(Note 3)	I_{AS}	1.6		A
Operating Junction and Storage Temperature Range	T_J, T_{STG}	- 55 to +150		°C

THERMAL PERFORMANCE				
PARAMETER	SYMBOL	IPAK/DPAK	ITO-220	UNIT
Junction to Case Thermal Resistance	$R_{\theta JC}$	2.5	6.25	°C/W
Junction to Ambient Thermal Resistance	$R_{\theta JA}$	62		°C/W

Notes: $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistances. The case thermal reference is defined at the solder mounting surface of the drain pins. $R_{\theta JA}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design. $R_{\theta JA}$ shown below for single device operation on FR-4 PCB in still air.

ELECTRICAL SPECIFICATIONS ($T_C = 25^\circ\text{C}$ unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static (Note 4)						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	BV_{DSS}	700	--	--	V
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	$V_{GS(TH)}$	2.0	3.1	4.0	V
Gate Body Leakage	$V_{GS} = \pm 30V, V_{DS} = 0V$	I_{GSS}	--	--	± 100	nA
Zero Gate Voltage Drain Current	$V_{DS} = 700V, V_{GS} = 0V$	I_{DSS}	--	--	1	μA
Drain-Source On-State Resistance	$V_{GS} = 10V, I_D = 1.5A$	$R_{DS(on)}$	--	0.83	0.9	Ω
Dynamic (Note 5)						
Total Gate Charge	$V_{DS} = 380V, I_D = 2.3A,$ $V_{GS} = 10V$	Q_g	--	9.7	--	nC
Gate-Source Charge		Q_{gs}	--	2.9	--	
Gate-Drain Charge		Q_{gd}	--	3.5	--	
Input Capacitance	$V_{DS} = 100V, V_{GS} = 0V,$ $f = 1.0MHz$	C_{iss}	--	482	--	pF
Output Capacitance		C_{oss}	--	34	--	
Gate Resistance	$F = 1MHz, \text{open drain}$	R_g	--	3.6	--	Ω
Switching (Note 6)						
Turn-On Delay Time	$V_{DD} = 380V,$ $R_{GEN} = 40\Omega,$ $I_D = 2.3A, V_{GS} = 10V,$	$t_{d(on)}$	--	20	--	ns
Turn-On Rise Time		t_r	--	54	--	
Turn-Off Delay Time		$t_{d(off)}$	--	34	--	
Turn-Off Fall Time		t_f	--	48	--	
Source-Drain Diode (Note 4)						
Forward On Voltage	$I_S = 4.5A, V_{GS} = 0V$	V_{SD}	--	--	1.4	V
Reverse Recovery Time	$V_R = 200V, I_S = 2.3A$ $di_f/dt = 100A/\mu s$	t_{rr}	--	176	--	ns
Reverse Recovery Charge		Q_{rr}	--	1.1	--	μC

Notes:

1. Current limited by package
2. Pulse width limited by the maximum junction temperature
3. $L = 50mH, I_{AS} = 1.6A, V_{DD} = 50V, R_G = 25\Omega, \text{Starting } T_J = 25^\circ\text{C}$
4. Pulse test: $PW \leq 300\mu s, \text{duty cycle} \leq 2\%$
5. For DESIGN AID ONLY, not subject to production testing.
6. Switching time is essentially independent of operating temperature.

ORDERING INFORMATION

PART NO.	PACKAGE	PACKING
TSM70N900CI C0G	ITO-220	50pcs / Tube
TSM70N900CH C5G	TO-251 (IPAK)	75pcs / Tube
TSM70N900CP ROG	TO-252 (DPAK)	2,500pcs / 13" Reel

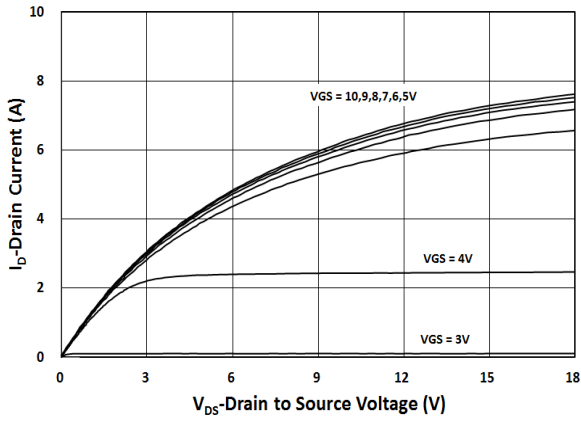
Note:

1. Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
2. Halogen-free according to IEC 61249-2-21 definition

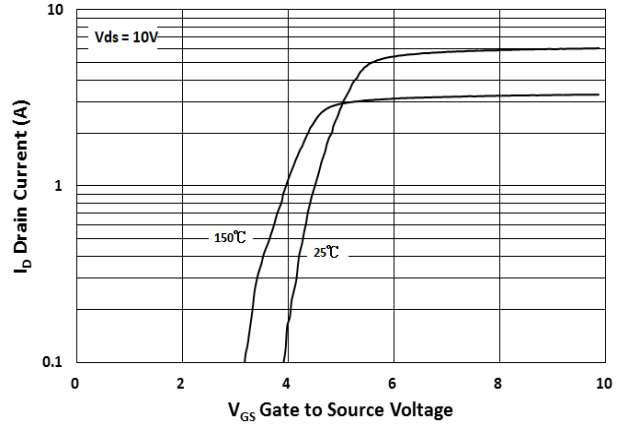
CHARACTERISTICS CURVES

($T_C = 25^\circ\text{C}$ unless otherwise noted)

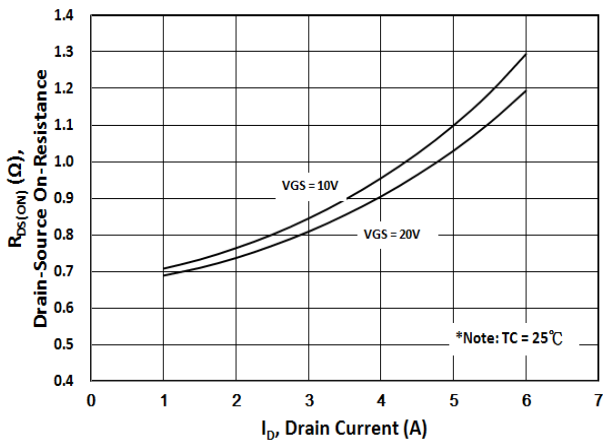
Output Characteristics



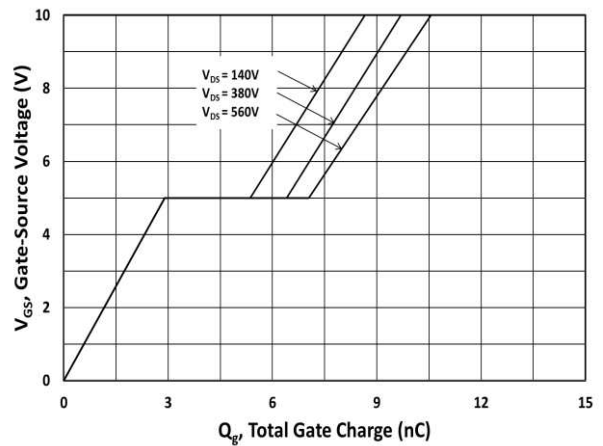
Transfer Characteristics



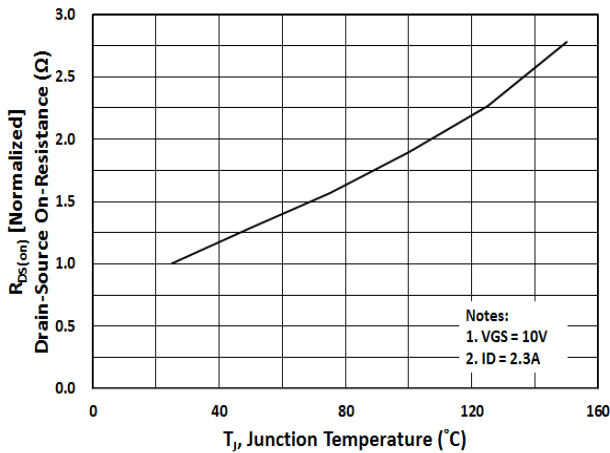
On-Resistance vs. Drain Current



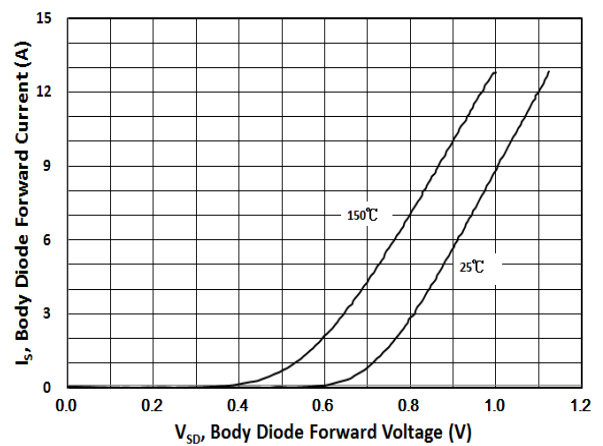
Gate-Source Voltage vs. Gate Charge



On-Resistance vs. Junction Temperature



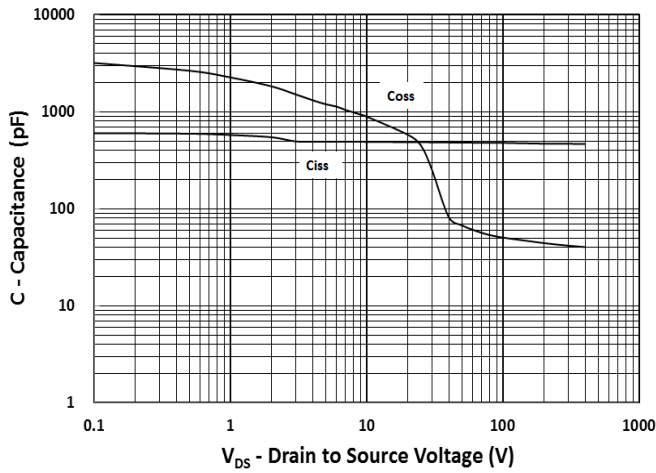
Source-Drain Diode Forward Current vs. Voltage



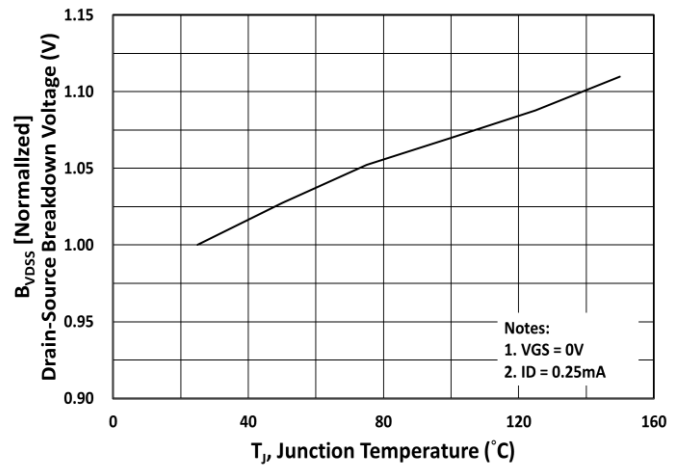
CHARACTERISTICS CURVES

($T_C = 25^\circ\text{C}$ unless otherwise noted)

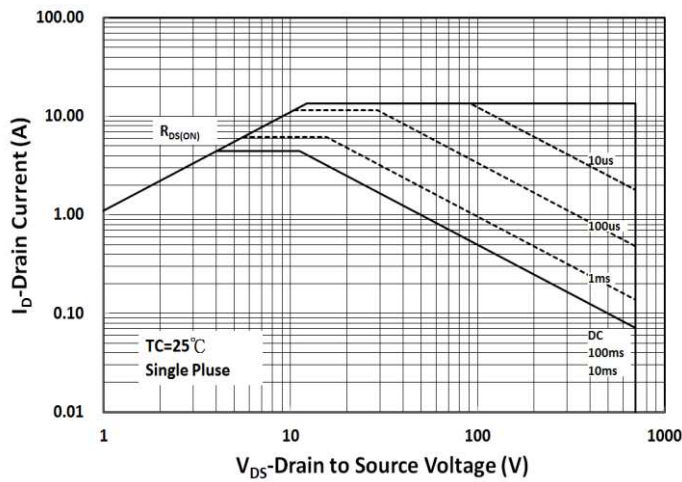
Capacitance vs. Drain-Source Voltage



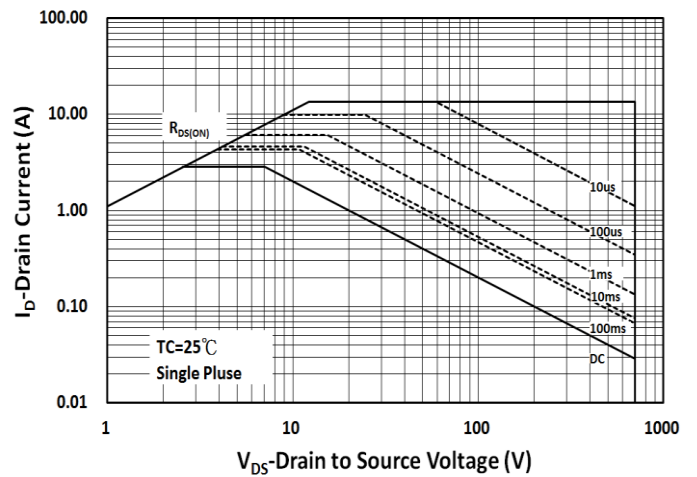
BV_{DSS} vs. Junction Temperature



Maximum Safe Operating Area (DPAK/IPAK)



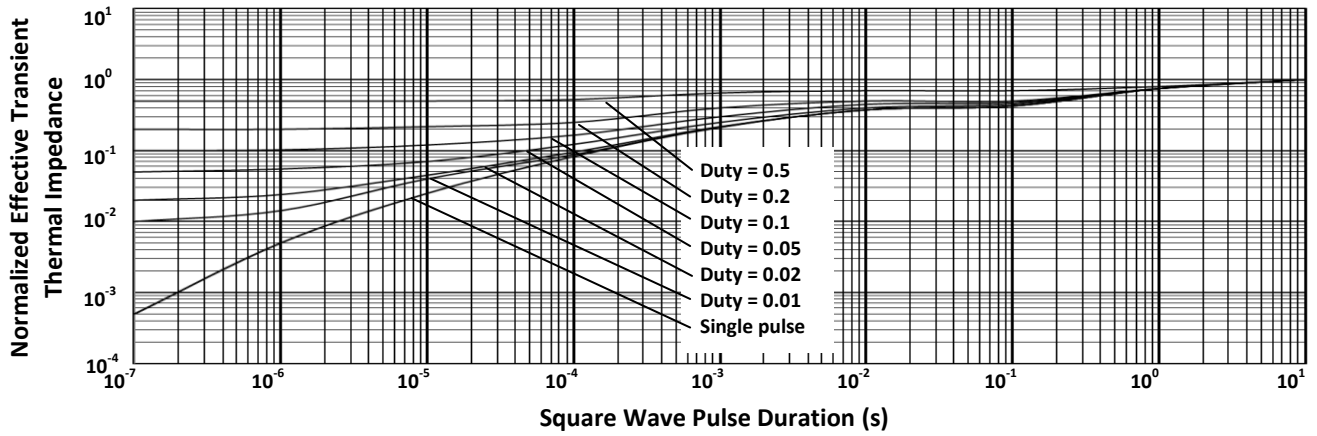
Maximum Safe Operating Area (ITO-220)



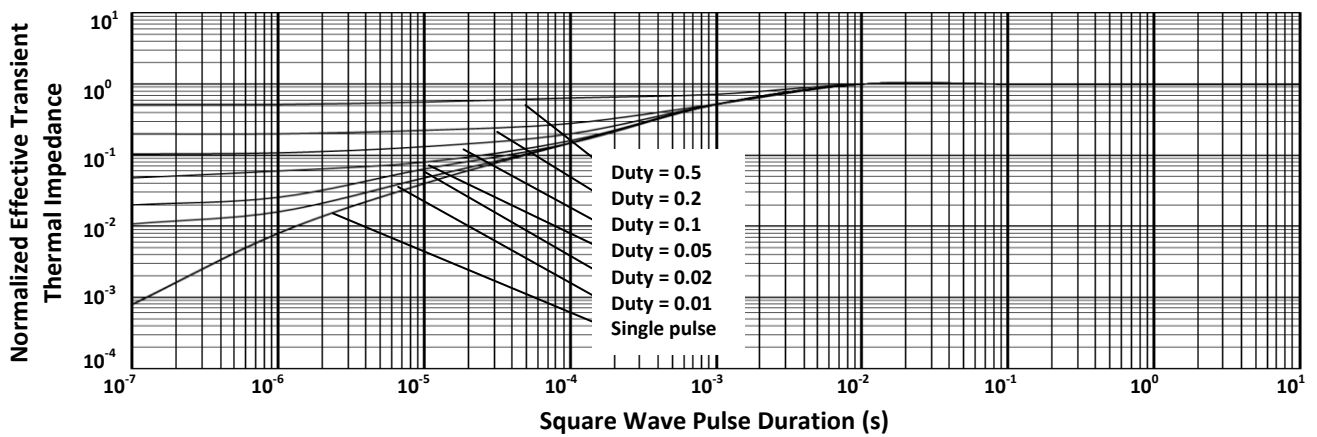
ELECTRICAL CHARACTERISTICS CURVES

($T_C = 25^\circ\text{C}$ unless otherwise noted)

Normalized Thermal Transient Impedance, Junction-to-Case (ITO-220)

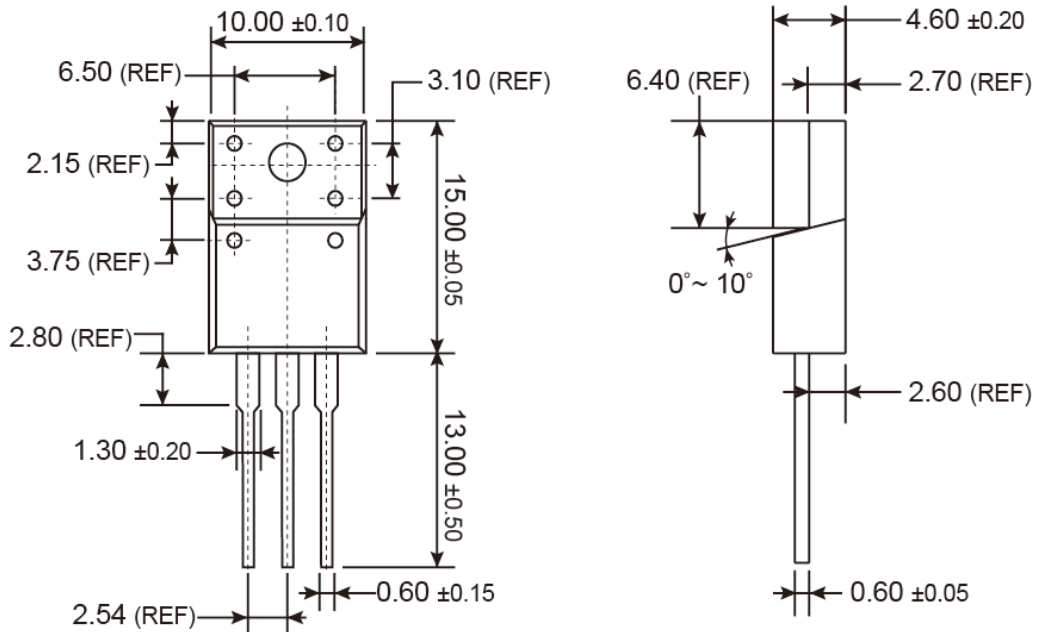


Normalized Thermal Transient Impedance, Junction-to-Case (DPAK/IPAK)

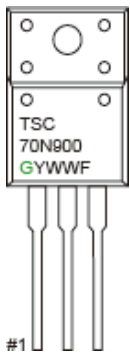


PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

ITO-220



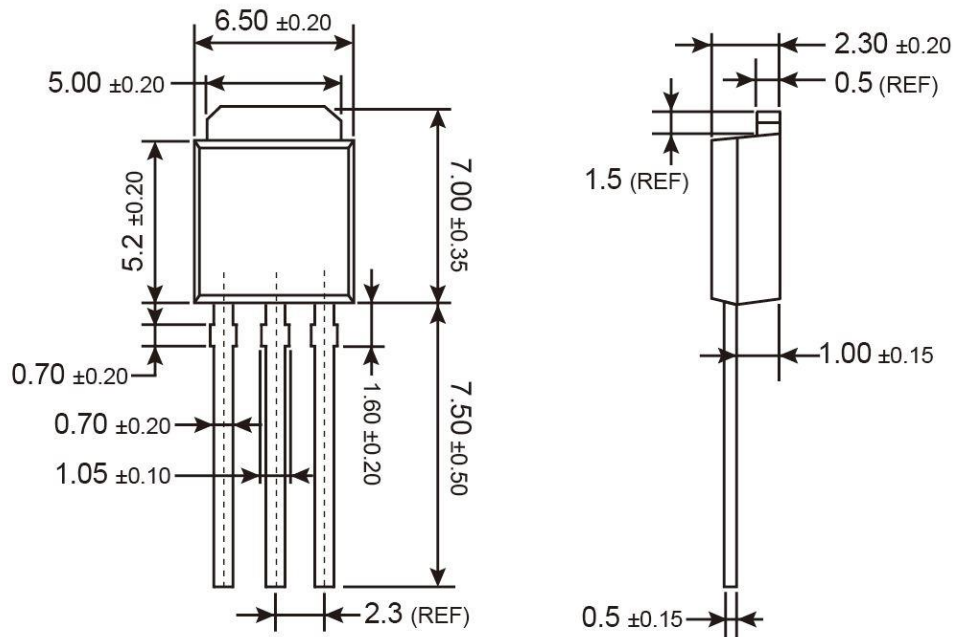
MARKING DIAGRAM



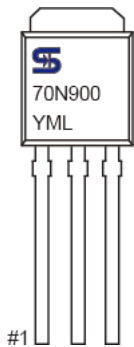
- G** = Halogen Free
- Y** = Year Code
- WW** = Week Code (01~52)
- F** = Factory Code

PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

TO-251

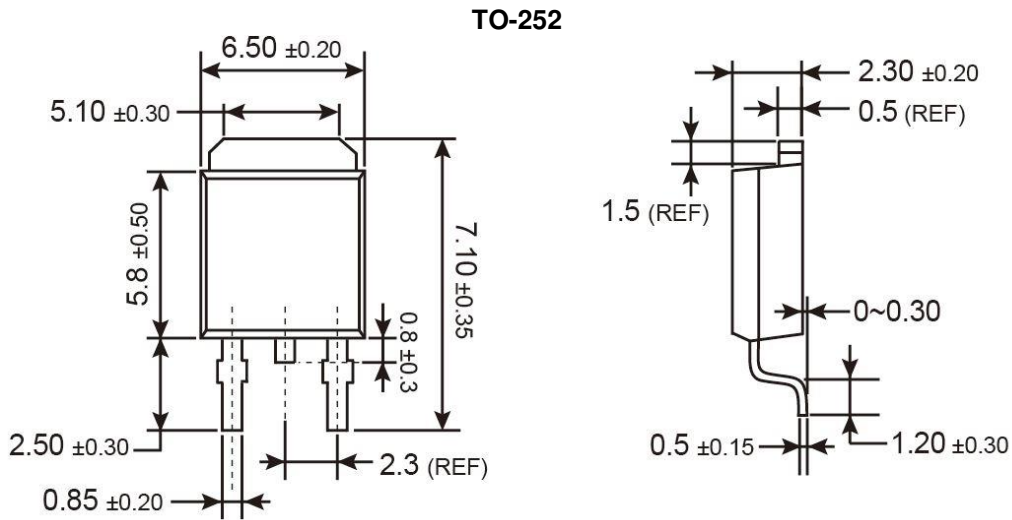


MARKING DIAGRAM

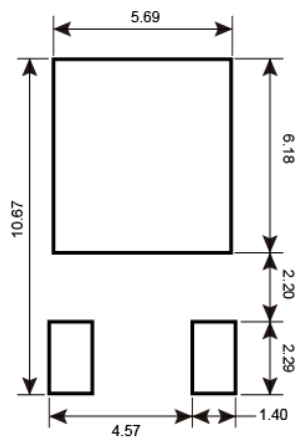


- Y** = Year Code
- M** = Month Code for Halogen Free Product
 - O** =Jan **P** =Feb **Q** =Mar **R** =Apr
 - S** =May **T** =Jun **U** =Jul **V** =Aug
 - W** =Sep **X** =Oct **Y** =Nov **Z** =Dec
- L** = Lot Code (1~9, A~Z)

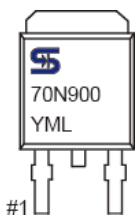
PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)



SUGGESTED PAD LAYOUT (Unit: Millimeters)



MARKING DIAGRAM



- Y** = Year Code
- M** = Month Code for Halogen Free Product
 - O** =Jan **P** =Feb **Q** =Mar **R** =Apr
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